

## POLISHING MEMBER AND APPARATUS

### ABSTRACT OF THE DISCLOSURE

A polishing member is provided in its polishing surface with a plurality of spiral grooves. The polishing surface is rotated while being slidably engaged with a semiconductor wafer to polish the wafer. During polishing, a pumping action is produced at the spiral grooves under a centrifugal force generated by rotation of the polishing member, and harmful large-diameter particles such as diamond particles from a dresser and abrasive particles in a polishing liquid can be discharged, together with the polishing liquid, through the spiral grooves toward an outer peripheral portion of the polishing member.